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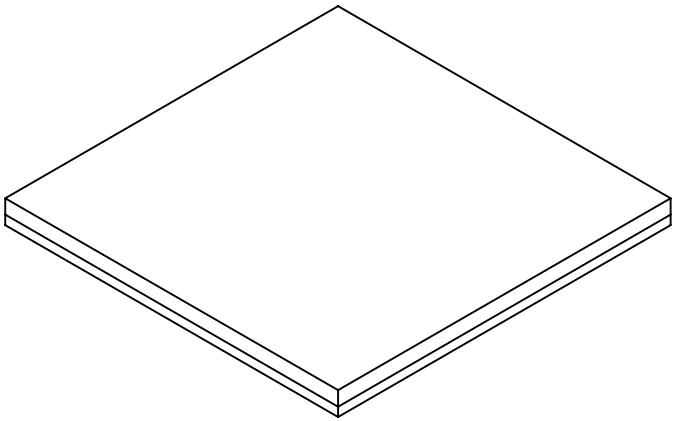
REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C03427	04/03/98	E.B.	HLE
01	REVISED TOLERANCES, DCN C04502	09/03/98	E.B.	KMN



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 100.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 10 X 10.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL: X.X ±0.10, X.XX ±0.05, X.XXX ±0.03
ANGULAR: ±1°

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

PROJECTION

APPROVALS	DATE
DRAWN: R. GUERRERO	03/27/98
CHECKED: M. EMMETTE	04/01/98
ENG'R: T. PANCZAK	04/01/98
RELEASED: M. ANTONIO	04/03/98

ANAM Industrial Co., LTD. Sungdong-Ku, Seoul, Korea
AMKOR Electronics, Inc. Chandler, Arizona, USA

amkor anam

TITLE: PACKAGE OUTLINE – CABGA 100, 11.00mm X 11.00mm, 2 LAYER, 1.00mm PITCH, LAMINATE SUBSTRATE, AAP

SIZE	SID NUMBER	DWG NUMBER	REV
B	N/A	73634	01

STEP DWG NUMBER/REV	CUST CODE	SCALE: 8:1	SHEET 1 OF 3
N/A	N/A		